



# Product Change Notification

**Change Notification #:** 114473 - 00  
**Change Title:** Intel® LLVT7028A103, LLVT7028A102, MHVT7037B001, FMVT7014E302, and LQVT7040B003 Processors  
PCN 114473-00, Manufacturing Site, Product Marking, Order Code, Label Transport Media, Additional Manufacturing Site and Transition from VIA Telecom to Intel Branding  
**Date of Publication:** May 13, 2016

## Key Characteristics of the Change:

Manufacturing Site, Product Marking, Order Code, Label, Transport Media

## Forecasted Key Milestones:

<b>Date Customer Must be Ready to Receive Post-Conversion Material:</b>	September 9, 2016
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## Description of Change to the Customer:

Please see the following changes to the Intel® LLVT7028A103, LLVT7028A102, MHVT7037B001, FMVT7014E302, and LQVT7040B003 Processor products:

1. In order to ensure a continuous supply of the Intel® LLVT7028A103, LLVT7028A102, MHVT7037B001, FMVT7014E302, and LQVT7040B003 Processors listed in the "Products Affected" Table below, Intel will continue to manufacture in Advanced Semiconductor Engineering, Inc. (ASE) and TeraPower Technology, Inc. (TPI) as well as now manufacture these products using an additional Intel qualified assembly site of Silicon Precision Industries (SPIL). The new manufacturing site has been certified equivalent (form, fit, function, and reliability) for the affected products and technologies of this change.
2. **Order Code:** Customers will now use a new MM# to order these part numbers. Please see the Products Affected/Intel Ordering Codes table for Post Conversion MM ordering information. Customers may receive mixed stock until pre-converted material is depleted.
3. **Marking:** The products listed on the Products Affected/Intel Ordering Codes table will transition from VIA Telecom to Intel branding. The branding transition is a visual change that does not affect the form, fit, function or reliability of the product. No other changes will be made to the product. Please see marking examples below:

Current VIA Telecom Branding	New Intel Branding
<p>MM# 947391</p> 	
<p>MM#: 947392</p> 	
<p>MM# 947394</p> 	
<p>MM# 947396</p> 	
<p>MM#: 947393</p> 	

- Labeling:** The currently used “VIA” Label will be changed to Intel standard labels to make sure the “VIA” products can be handled by the Intel warehouse system.

**Moisture Barrier Bag Label – VIA Telecom:**

<b>VIA TELECOM COMPANY Limited</b>			
PROJECT NAME: 7018B101/TMBW34B-64M32M			
PRODUCT NAME: CBP7.2			
PACKAGE LEAD: TFBGA 321 10*13			
TOTAL QUANTITY: 500		PACKED: 2012/03/15	
DATE CODE:	LOT.NO.:	QTY:	
120501	H3F739.1	500	
120501	H3F739.1	500	
120501	H3F739.1	500	
120501	H3F739.1	500	
120501	H3F739.1	500	
120501	H3F739.1	500	

**Intel:**


(P) CUST PROD:	(1B) BOX:
(V) SUPPLIER: 04195 [Barcode]	<b>INTEL</b>
(1P) IPN: AFPC202 [Barcode]	MAX REFLOW 250 °C TEMP [Barcode]
(S) SPEC: S R1YX [Barcode]	LEVEL 3 HOURS 168 BAG SEAL DATE 17JUL14 [Barcode]
(30P) MM#: 937337 [Barcode]	
(1T) LOT: W4236L03 [Barcode]	(Q) QTY: 400 [Barcode]
(1T) LOT:	(9D) DATE: 1423 [Barcode]
RoHS COMPLIANT, e1	(9D) DATE:
	ASSEMBLED IN TAIWAN

**Finished Goods (Inner Box) - VIA Telecom:**



VIA TELECOM COMPANY Limited			
PROJECT NAME: 7018B101/TMBW34B-64M32M			
PRODUCT NAME: CBP7.2			
PACKAGE LEAD: TFBGA 321 10*13			
TOTAL QUANTITY: 500		PACKED: 2012/03/15	
DATE CODE:	LOT,NO.:	QTY:	
120501	H3F739.1	500	
120501	H3F739.1	500	
120501	H3F739.1	500	
120501	H3F739.1	500	
120501	H3F739.1	500	
120501	H3F739.1	500	

**Intel:**

With Box ID

(P) CUST PROD: (1B) BOX: VW000001  


(V) SUPPLIER: 04195 **INTEL**

(1P) IPN: AFPC202 **MAX REFLOW** 250 °C  
**TEMP**   
**LEVEL 3** **HOURS** 168  
**BAG SEAL DATE** 17JUL14  


(S) SPEC: S R1YX (30P) MM#: 937337

(1T) LOT: W4236L03 (Q) QTY: 400 (9D) DATE: 1423

(1T) LOT: (Q) QTY: (9D) DATE:

RoHS COMPLIANT, e1

ASSEMBLED IN TAIWAN

**Transport Label (Outer Box) - VIA Telecom**

VIA TELECOM COMPANY Limited			
PROJECT NAME: 7018B101/TMBW34B-64M32M			
PRODUCT NAME: CBP7.2			
PACKAGE LEAD: TFBGA 321 10*13			
TOTAL QUANTITY: 500		PACKED: 2012/03/15	
DATE CODE:	LOT.NO.:	QTY:	
120501	H3F739.1	500	
120501	H3F739.1	500	
120501	H3F739.1	500	
120501	H3F739.1	500	
120501	H3F739.1	500	
120501	H3F739.1	500	

**Customer specific labels, example Huawei**

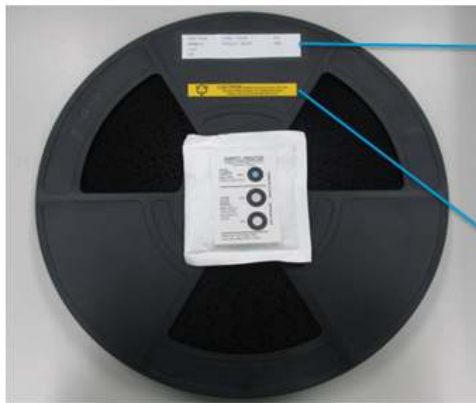
(K) PO No: <b>VRN810267088</b>		
(P) Customer P/N: <b>39200615</b>		
(1P) Manufacturer P/N: <b>CBP8.2D</b>		
(V) Vendor Code: <b>Z007AS</b>		
(M) Manufacturer: <b>VIA TELECOM</b>		
(4L) Country of Origin: <b>TAIWAN</b>		
(9D) Date Code: <b>1210</b>	(1T) Lot No: <b>NGX238.00</b>	(Q) QTY: <b>2000</b>
		
(9D) Date Code: <b>1210</b>	(1T) Lot No: <b>NGX238.00</b>	(Q) QTY: <b>2000</b>
		

**Intel:**

FROM: ADC 5000 W CHANDLER BLVD CHANDLER, AZ 85226	TO: AC ROCHESTER 2925 DAVISON ROAD REC ARE FLINT, MI 48556
(3S) PKG ID:	SUPPLIER+SALESORDER
	
(K) PO NUMBER:	PO NUMBER
	
(P) CUSTOMER PROD ID:	CUSTOMER PART NO
	
(Q) QUANTITY:	1234567 EA
	
(Z) SPECIAL:	SPECIAL DATA
	
INTEGRATED CIRCUITS	
PACKAGE WEIGHT:	
27.00 LBS	
12.25 KGS	
PACKAGE COUNT:	
3333 OF 4444	

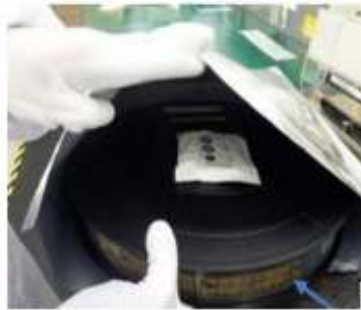
5. **Packing:** The currently used “VIA” Packing will be changed to Intel standard packing to make sure the “VIA” products can be handled by the Intel warehouse system.

**Intel Corporation Tape and Reel Packing:**



INTEL FPO# W5496L02	S SPEC: S R128 PRODUCT: 936079	QTY: 1680
CUST P/N:		

 **CAUTION** SENSITIVE ELECTRONIC DEVICES  
DO NOT OPEN EXCEPT AT APPROVED FIELD  
FORCE PROTECTIVE WORK STATION.



IN SUPPLIER CODE	INTEL	IN BOX
IN P/N: WPC02		MAX REEL W: 330 mm
S SPEC: S R128	QTY: 1680	TEMP: 25°C
ITL LOT: W5496L02	ICQ QTY: 480	LEVEL: 3
ITL CUST	ICQ QTY:	REEL DATE: 12/21/14
Read COMPLIANT #		REEL DATE:

ASSEMBLED IN TAIWAN



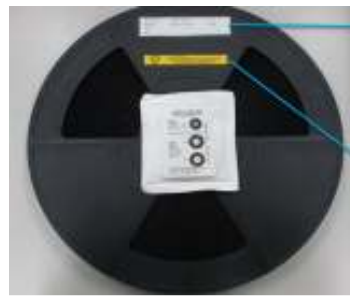
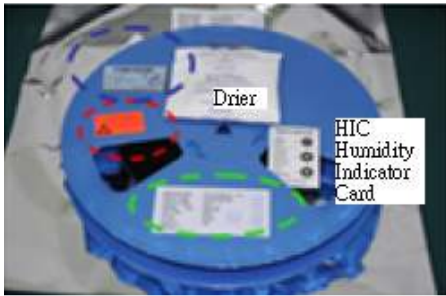
IN SUPPLIER CODE	INTEL	IN BOX
IN P/N: WPC02		MAX REEL W: 330 mm
S SPEC: S R128	QTY: 1680	TEMP: 25°C
ITL LOT: W5496L02	ICQ QTY: 480	LEVEL: 3
ITL CUST	ICQ QTY:	REEL DATE: 12/21/14
Read COMPLIANT #		REEL DATE:

ASSEMBLED IN TAIWAN

Comparison

VIA Telecom (old)

Intel (new)



ESD Mark; Carton label  
Customer special label  
VTC Box label + RoHS label

**Intel Corporation Tray packing:**



(P) CUST PROD:		(1B) BOX:	
(V) SUPPLIER: 04195	INTEL		MAX REFLOW 250 °C
(1P) IPN: AFPC202			TEMP
(S) SPEC: S R1YX	(30P) MM#: 937337		LEVEL 3 HOURS 168
(1T) LOT: W4236L03	(Q) QTY: 400		BAG SEAL DATE 17JUL14
(1T) LOT:	(Q) QTY:	(9D) DATE: 1423	
RoHS COMPLIANT, e1		(9D) DATE:	ASSEMBLED IN TAIWAN



(P) CUST PROD:		(1B) BOX: VW000001	
(V) SUPPLIER: 04195	INTEL		MAX REFLOW 250 °C
(1P) IPN: AFPC202			TEMP
(S) SPEC: S R1YX	(30P) MM#: 937337		LEVEL 3 HOURS 168
(1T) LOT: W4236L03	(Q) QTY: 400		BAG SEAL DATE 17JUL14
(1T) LOT:	(Q) QTY:	(9D) DATE: 1423	
RoHS COMPLIANT, e1		(9D) DATE:	ASSEMBLED IN TAIWAN

## Comparison

### VIA Telecom (old)



### Intel (new)



Please note that we will not change the maximum number of trays (10+1). Therefore we will ship boxes with “partial stack of trays” but not full stacks.



### **Customer Impact of Change and Recommended Action:**

The branding, packing and labeling transition is a visual change that does not affect the form, fit, function or reliability of the product. It should be fully understood as to how this change must be accommodated and implemented within the customer’s processes.

All impacted products with the new marking, packing and labeling have identical quality and reliability as the current products. Customers may receive shipments with either/both part markings until the current inventory has been depleted. Marking will not be mixed within an intermediate box.

Please contact your local Intel Field Sales Representative if you have any further questions about this change.

## Products Affected / Intel Ordering Codes:

Marketing Name	Stepping	Pre Conversion Product Code	Pre Conversion S-Spec	Pre Conversion MM#	Post Conversion Product Code	Post Conversion S-Spec	Post Conversion MM#
Intel® LLVT7028A103 Processor	A1	LLVT7028A103	S LLKQ	947391	KJVT7028A103	S LLUV	951295
Intel® LLVT7028A102 Processor	A1	LLVT7028A102	S LLKG	947392	KJVT7028A102	S LLUW	951292
Intel® MHVT7037B001 Processor	B0	MHVT7037B001	S LLKR	947393	MWVT7037B001	S LLUU	951240
Intel® FMVT7014E302 Processor	E3	FMVT7014E302	S LLKF	947394	KTVT7014E302	S LLUX	951293
Intel® LQVT7040B003 Processor	B0	LQVT7040B003	S LLKT	947396	MYVT7040B003	S LLVB	951381

## PCN Revision History:

**Date of Revision:**

May 13, 2016

**Revision Number:**

00

**Reason:**

Originally Published PCN



# Product Change Notification

## 114473 - 00

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**Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.**

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